



**TARGET THICKNESS: 0.078"**  
**NUMBER OF LAYERS: 08**

# MULTILAYER PCB CONSTRUCTION SHEET

If there are max thickness requirements beyond +/- .10% overall - non-standard construction should be ordered and notes added.

<b>8 Layer StackUp (0.078") L08-078-1oz1oz</b>		<b>Thickness (inches)</b>
<b>Layer 1</b>	<b>1 oz foil plated to approximate* thickness 0.0024"</b>	0.0024
Prepreg	Bonding ply (1x1080, 1x7628) Average Dielectric Constant 4.5	0.0097
<b>Layer 2</b>	<b>1 oz foil thickness</b>	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.01
<b>Layer 3</b>	<b>1 oz foil thickness</b>	0.0014
Prepreg	Bonding ply (2x1080, 1x7628) Average Dielectric Constant 4.5	0.0119
<b>Layer 4</b>	<b>1 oz foil thickness</b>	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.01
<b>Layer 5</b>	<b>1 oz foil thickness</b>	0.0014
Prepreg	Bonding ply (1x7628, 2x1080) Average Dielectric Constant 4.5	0.0119
<b>Layer 6</b>	<b>1 oz foil thickness</b>	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.01
<b>Layer 7</b>	<b>1 oz foil thickness</b>	0.0014
Prepreg	Bonding ply (1x7628, 1x1080) Average Dielectric Constant 4.5	0.0097
<b>Layer 8</b>	<b>1 oz foil plated to approximate* thickness 0.0024"</b>	0.0024
<b>"Thickness does not include soldermask or surface finish"</b>		<b>0.0864</b>

## NOTES: